



Shenzhen Dinghua Technology Development Co., LTD.

Product Introduction

Company Profile

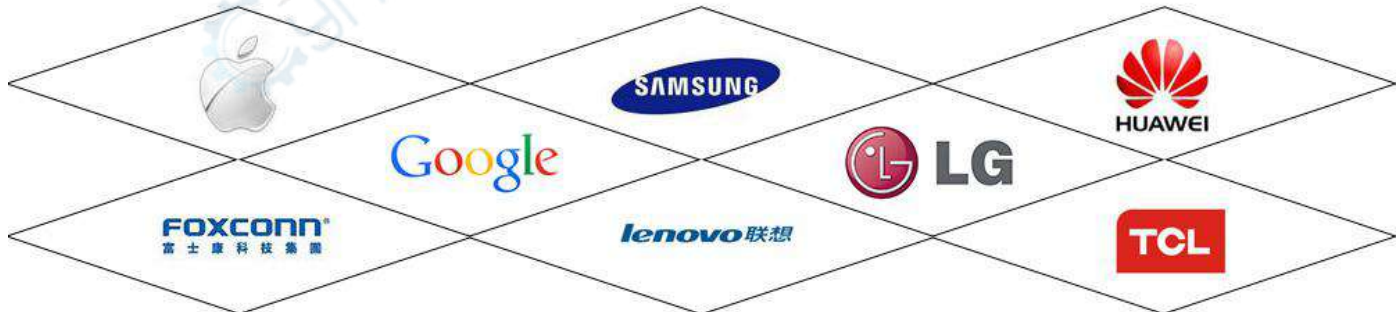


Shenzhen Dinghua Technology Development Co., LTD.

- Established in 2011 , years experiences in SMT/BGA rework industry.
- Research, Develop, Design, Manufacture and Export BGA Rework Station, Automatic Soldering Machine, Automatic Dispenser, Automatic Locking Screw Machine.
- 38 Patents And 97 Quality Control Process
- China National High-Tech Enterprise, IPC certified, SMT Association Membership, etc.
- One of leading manufacturers in China as a professional Rework Solution Provider.



Business Partners



Product Presentation



Honored Client



BGA Rework Station

Model:DH-5860

- Intelligent man-machine & PLC control
- Applicable BGA size: 2*2-80*80mm
- Vacuum pen for handing BGA chip
- Repair Success Rate: 99%+
- Temp Accuracy:±2°C
- Touch screen control
- Manual operation

Specifications

Power	4800W
Top heater	Hot air 800W
Bottom heater	Hot air 1200W, Infrared 2700W
Power supply	AC220V±10% 50/60Hz
Dimension	L635*W600*H560 mm
Positioning	V-groove PCB support, and with external universal fixture
Temperature control	K type thermocouple, closed loop control, independent heating
Temperature accuracy	±2°C
PCB size	Max 450*550 mm, Min 20*20 mm
Workbench fine-tuning	±15mm forward/backward,±15mm right/left
BGA chip	80*80-2*2mm
Minimum chip spacing	0.15mm
Temp Sensor	1(optional)
Net weight	48kg

General Usages



BGA/IC replacement



motherboard repair



Xbox playstation repair



Server CPU repair



iPhone repair

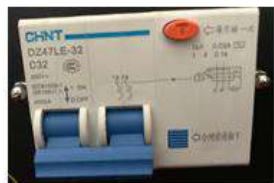


iPad, Macbook repair

Product Image



Movable PCB shelf & universal fixtures



Leakage switch



Handle control



Head lamp



Fitting handle



IR heater



Bottom heater height adjust



Cross-Flow Cooling Fan



Right & Left heater button



HD Touch Screen



Emergency Stop



Start button



Headlamp control button



Vaccum pen

Function



Operation System

- Manual operation mode
- New operator-friendly user interface
- One-stop soldering, desoldering
- Built-in PLC precise control, Intelligent man-machine, digital system setting



Manual control handle

To control the head move up/down and move forward /backward

Name	Temp	Time	Temp	Time	Temp	Time	Temp	Time
Start	260	10	260	10	260	10	260	10
Preheat	260	10	260	10	260	10	260	10
Heat	260	10	260	10	260	10	260	10
Peak	260	10	260	10	260	10	260	10
Soak	260	10	260	10	260	10	260	10
Cool	260	10	260	10	260	10	260	10
End	260	10	260	10	260	10	260	10

Brand-new operator-friendly user interface

1. Easy to master the operation flow within minutes
2. Setting different temperature profile according to various types of BGA
3. Storage the same temperature profile for same PCB to save time



Temperature curve setting

Instantly analyze temperature on touch screen, which can effectively avoid false welding, fake welding



Newly-upgraded Touch Screen Control

7 inches HD touch screen operation system
English, Spanish and other languages systems available.



Bottom heater height adjust

1. Ensure 3-5mm suitable distance between PCB and nozzle
2. Slight adjustment to get PCB closer to bottom nozzle for better heating



Function



Precise Temperature Control System

Even and focused heating effectively avoid fake or bad soldering and increase success rate of repairing.

- 8 segments rising temperature/constant time/temperature rising slope, It can save ten thousand groups temperature curves.
- It uses k-type thermocouple closed-loop control and PID automatic temperature compensation system, together with PLC and temperature module to enable precise temperature deviation to ± 2 degree centigrade.
- The external sensor can detect temperature precisely, analyze and calibrate the real temperature curve accurately at any time.

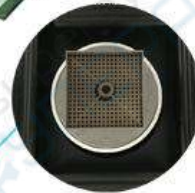


Top Heater (Hot Air 800W)

1. Reflow vent design ensure focused and even heating, effectively increase success rate of repairing chips.
2. Top hot air flow is adjustable, to meet the demand of any chips.



- Top heater can be equipped with different size of nozzles for different size of chip.
- Reflow vent design makes heating even, effectively increase success rate of repairing



2nd Bottom heater : hot air 1200W



3rd IR preheater : 2700W

1. Three independent temperature zones adopt PID temp control
2. Infrared heating is more easily absorbed by PCB.
3. Prevent PCB from deformation more effectively
4. Make heating more evenly
5. Make the temp rising more steadily and stably



Vacuum pen

There are internal vacuum pump and external vacuum pen for assisting to fetch the BGA chip



启动 START 工作照明 HEADLAMP

Start button for heating
Headlamp control button



Function



Safety system

- Equipped with emergency stop when abnormal accident happens, with a double over-heating protection control.
- Powerful cross-flow cooling fan
- Leakage switch
- Voice warning
- Limit bar



Leakage Switch

Automatic tripping in case of leakage
Check once monthly is preferred.



Voice warning

5 seconds before soldering/desoldering process complete.



Limit bar

To protect the head in the right height
from falling too low



Powerful Cross-flow cooling fan

1. Cooling fan produces cross cool air flow as soon as soldering/desoldering process finish, which effectively avoid deformation of PCB.
2. Extend continuous working and life cycle



Right heater & left heater control button



Emergency stop button

1. Press emergency stop in case of any emergency.
2. Automatic power-off switch in case of emergency.



Function

Other Functions



Flexible ways available for PCB position

1. ①Position: V-groove+②PCB bracket+③universal fixtures. Different ways for different PCB.

Bliwing Cylinder

2. Whole PCB table can be moved to left or right.

3. Composed of 16mm chrome plated rod. Very stable and strong.

LED headlamp

1. Super bright

2. Imported from Taiwan.

3. It can help you clearly see the melting condition of solder ball and check if there is any dirt on PCB and chip.



Fitting handle

Rotate the handle to lock the angle of the upper zone



Top air flow adjust button

1. Adjust top air flow to meet the demands of tiny chips
2. Prevent small bga chip from moving by strong air flow
3. Adjust the air flow to cool when the temp is too hot

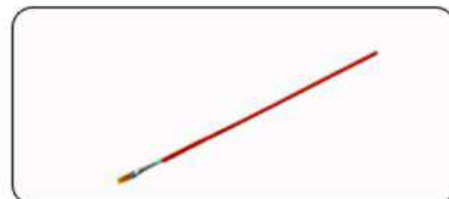


USB port

1. Transfer information(temperature profile) to computer.
2. Update system.



Packing List



Certification



Shenzhen Dinghua Technology Development Co., LTD.

深圳市鼎华科技发展有限公司



Thank You!

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